CLAIMS

1. An epoxy resin composition, comprising:

an epoxy resin;

a curing agent;

alumina particles; and

a silane compound which does not have a functional group that is reactive with an epoxy group and which has a functional group that is unreactive with an epoxy group, wherein the silane compound has a structure in which the functional group that is unreactive with an epoxy resin is bound to a silicon atom, or is bound to a silicon atom via a chain hydrocarbon group having 1 to 5 carbon atoms.

2. The epoxy resin composition according to claim 1, wherein a content of the silane compound is from 0.01% by mass to 20% by mass with respect to a total amount of the epoxy resin.

3. The epoxy resin composition according to claim 1 or 2, wherein the functional group that is unreactive with an epoxy resin is at least one selected from the group consisting of a (meth)acryloyl group, a (meth)acryloyloxy group, and a vinyl group.

4. The epoxy resin composition according to any one of claims 1 to 3, wherein the silane compound comprises 3-methacryloxypropyltrimethoxysilane.

5. The epoxy resin composition according to any one of claims 1 to 4, wherein a content of the alumina particles is 50% by volume or more with respect to a total amount of the epoxy resin composition.

6. The epoxy resin composition according to any one of claims 1 to 5, further comprising silica particles.

7. An electronic component device, having an element sealed with the epoxy resin composition according to any one of claims 1 to 6.